External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03746	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01124	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03746	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.377	99.77	400.0777
			Subtotal	37.46316	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.83861	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.91376	10.0	63.3
	Filler	Silica fused	60676-86-0	50.26697	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11828	0.2	1.266
			Subtotal	59.13762	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.33561	100.0	25
			Subtotal	2.33561	100	25
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00361	2.0	0.0386
	Lead alloy	Silver (Ag)	7440-22-4	0.00451	2.5	0.04825
	Lead alloy	Lead (Pb)	7439-92-1	0.1722	95.5	1.84315
			Subtotal	0.18032	100	1.93
Die		Lead Dioxide (PbO2)	1309-60-0	0.00395	0.9	0.0423
	Doped silicon	Silicon (Si)	7440-21-3	0.43514	99.1	4.6577
			Subtotal	0.43909	100	4.7
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.44421	100.0	4.7548
			Subtotal	0.44421	100	4.7548
			Total	100.00001	100	1070.3848

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.